DOCUMENT CHANGE REQUEST

DCR number	568	Changes required for: General	Originator: Steve Thacker - ESCC
Date: 2010/01/12		Date sent: 2010/01/12	Organisation:
Status: IMPLEMENTED			

Title:	Generic Specification for Discrete Semiconductor Components		
Number:	5000	Issue:	5

Other documents affected:

Page:

Page 28 Para 12.4/Chart F4

Paragraph:

Page 28 Para 12.4/Chart F4

Original wording:

Proposed wording:

Chart F4
Add missing test box for Moisture Resistance, as follows (see attached mark-up), in The Environmental/Mechanical Subgroup (2nd column) between Temperature Cycling and Seal

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Moisture
Resistance
Para. 8.15

Justification:

This is an editorial error. The Moisture resistance test box in Chart F4 was wrongly removed during implementation of DCR399 on 5000 issue 3.

Attachments:

DCR_Attachment_for_5000_issue_5.pdf, null

Modifications:

N/A

Approval signature:

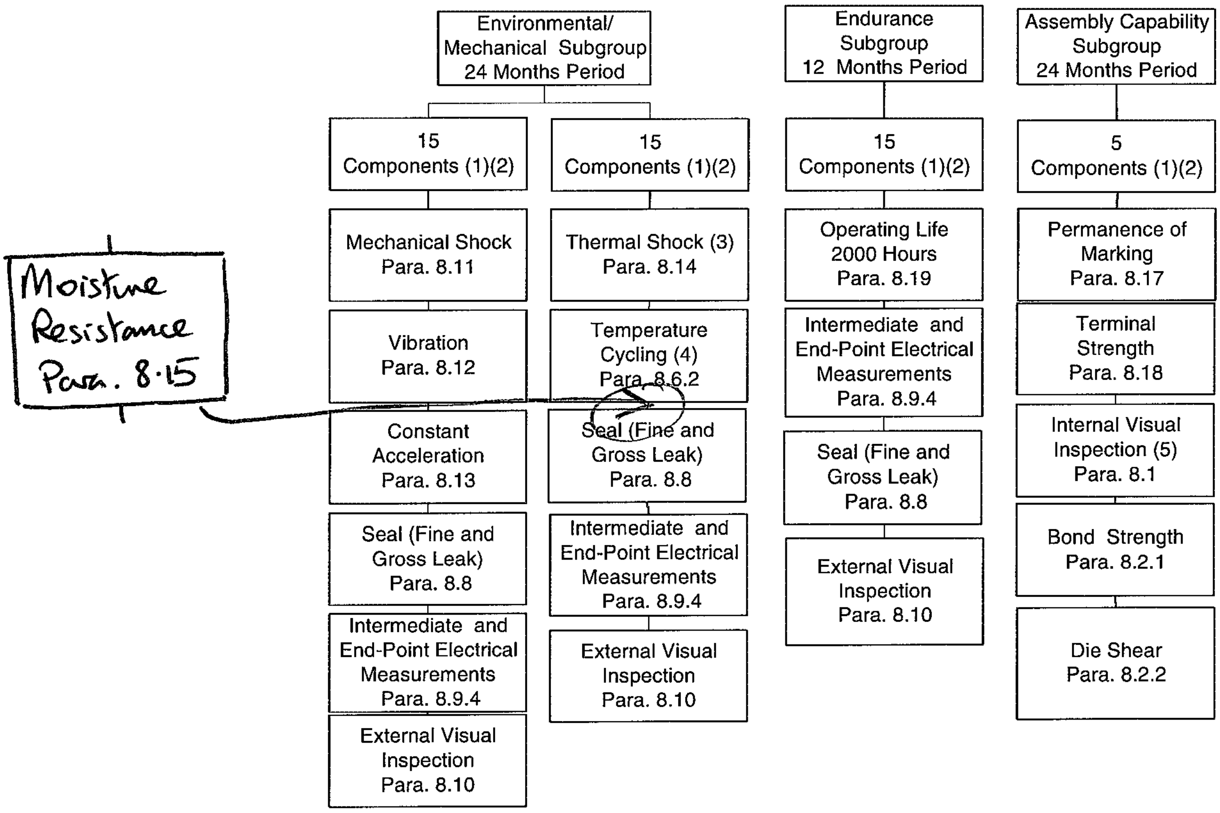
Date signed:

2010-01-12

MARK-UP FOR DCR S. Thacker
12/01/10.

point prior to Initial measurements of Parameter Drift Values.
2. The lot failure criteria of Para. 6.4 apply to this test.
3. Performed on a sample basis.
4. For components with hot solder dip final lead finish the hot solder dip processing shall be performed at any time prior to Room Temperature Electrical Measurements during Screening Tests. The requirements for hot solder dip are specified in ESCC Basic Specification No. 23500.
5. Measurements of Parameter Drift Values need not be repeated in Room Temperature Electrical Measurements.
6. Check for Lot Failure shall take into account all electrical parameter failures that may occur during Screening Tests in accordance with Para. 8.9.1, 8.9.2, 8.9.3 subsequent to HTRB Burn-in.
7. Radiographic Inspection may be performed at any point during Screening Tests after serialisation. It is not applicable for diodes with transparent packages.

12.4 CHART F4 - QUALIFICATION AND PERIODIC TESTS



NOTES:
1. For distribution within the subgroups see Para. 7.1.2 for qualification and qualification maintenance and Para. 7.4 for Lot Validation Testing.
2. No failures are permitted.
3. Only applicable to axial lead glass diodes.
4. Not applicable to axial lead glass diodes.
5. The components shall be deencapsulated using suitable means to facilitate Internal Visual Inspection, Bond Strength and Die Shear.